

/ Descriptions

TO-92 NPN Silicon NPN transistor in a TO-92 Plastic Package.

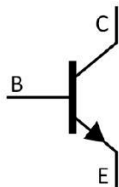
/ Features

$G_{pe}=29\text{dB}$ ($f=10.7\text{MHz}$)

High power Gain: $G_{pe}=29\text{dB(Typ.)}$ ($f=10.7\text{MHz}$).

/ Applications

High frequency amplifier applications.

/ Equivalent Circuit**/ Pinning**

PIN1 Base PIN 2 Collector PIN 3 Emitter

/ hFE Classifications & Marking

h _{FE} Classifications Symbol	R	O	Y
h _{FE} Range	40~80	70~140	120~240

2SC380TM

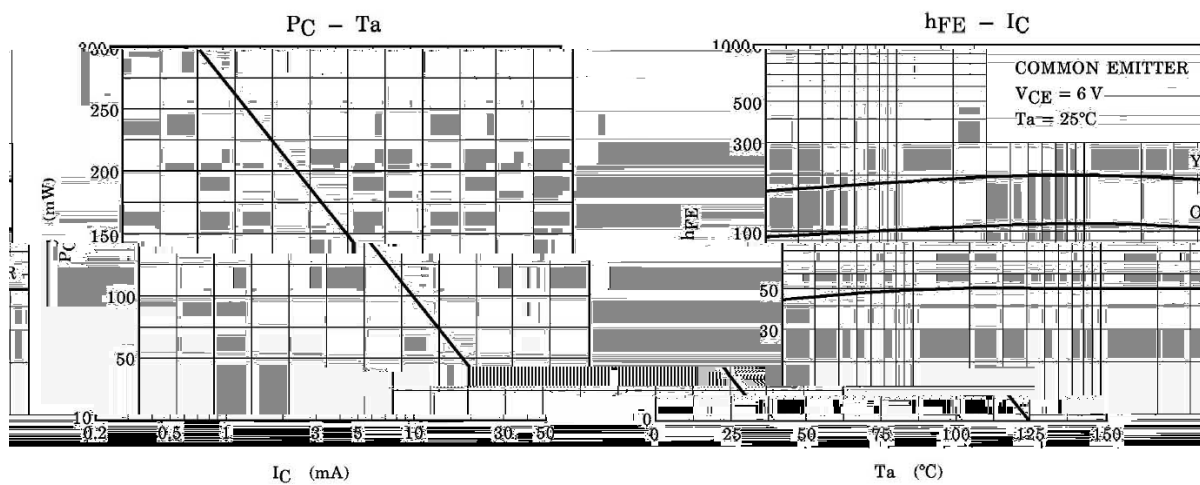
Rev.E Mar.-2016



DATA SHEET

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	35	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	4.0	V
Collector Current - Continuous	I_C	50	mA
Emitter Current - Continuous	I_E	-50	mA

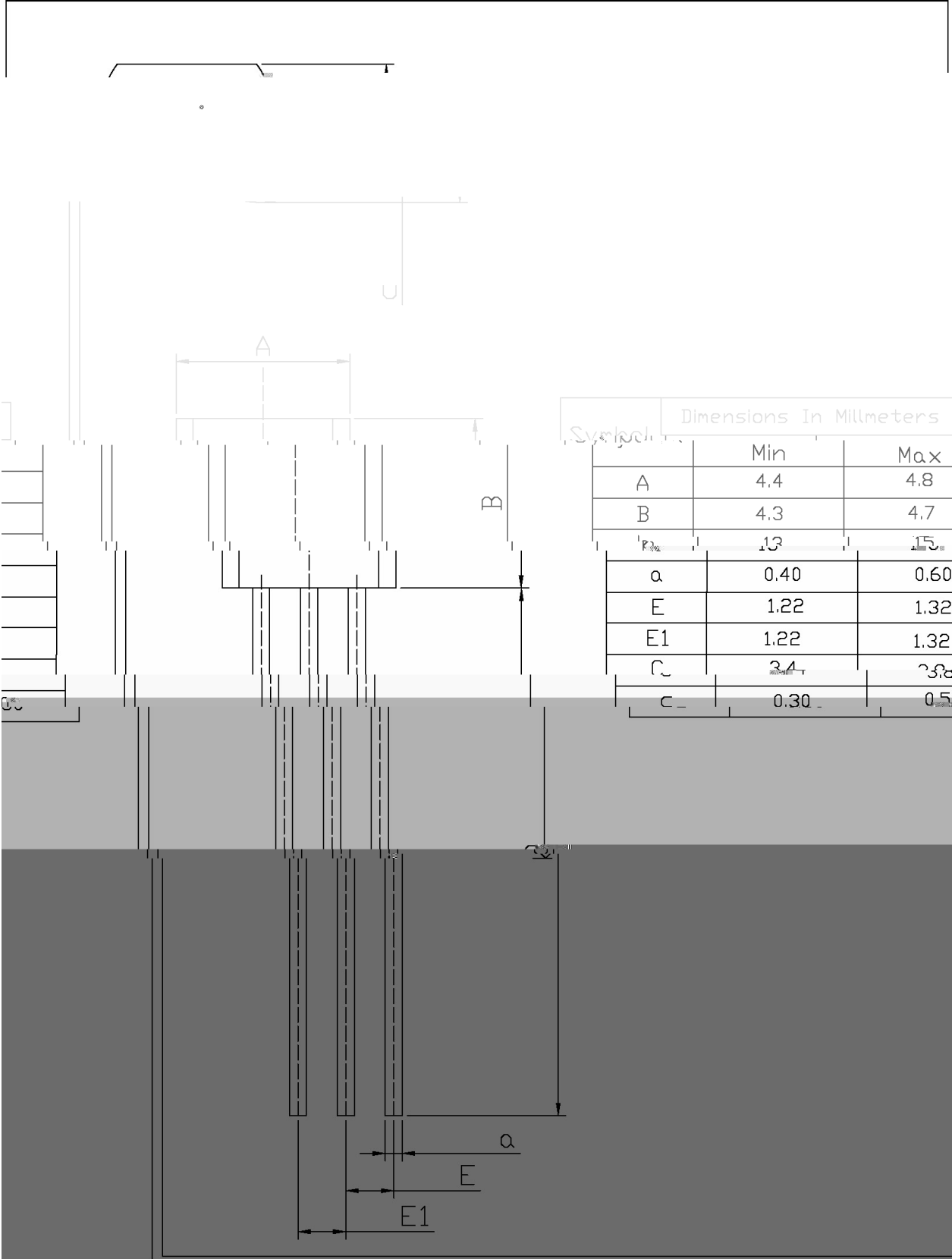
/ Electrical Characteristic Curve



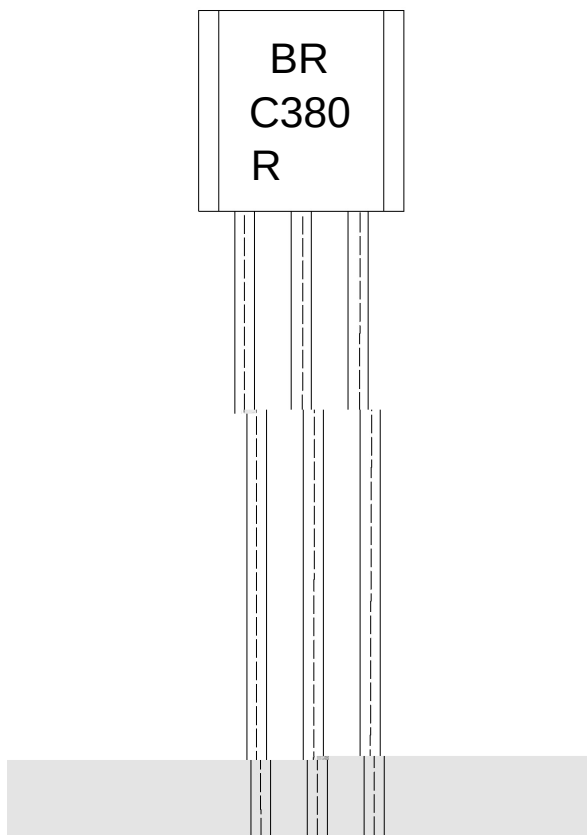
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



BR:

C380

R: h_{FE}

Note:

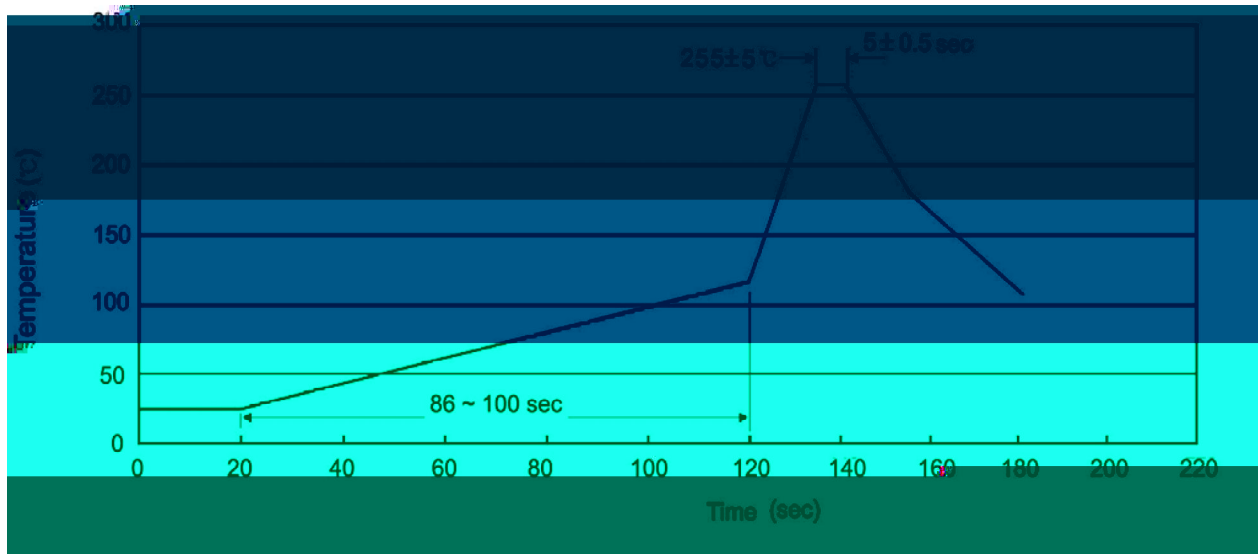
BR: Company Code.

C380: Product Type.

R: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	只纸带	纸带盒	纸带层盒	盒箱	只箱	盒	箱
							小箱 , 大箱

/ Notices